SN54BCT25244, SN74BCT25244 25-Ω OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS064A - JUNE 1990 - REVISED NOVEMBER 1993

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater
- Distributed V_{CC} and GND Pins Minimize Noise Generated by the Simultaneous Switching of Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (JT, NT)

description

These 25- Ω octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These buffers are capable of sinking 188-mA IOI, which facilitates switching $25-\Omega$ transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more reliable system operation.

When the output-enable $(1\overline{OE} \text{ and } 2\overline{OE})$ inputs are low, the device transmits data from the A inputs to the Y outputs. When $1\overline{OE}$ and $2\overline{OE}$ are high, the outputs are in the high-impedance state.

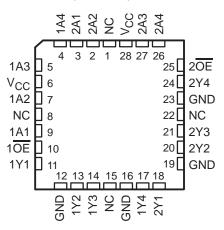
The SN54BCT25244 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74BCT25244 is characterized for operation from 0°C to 70°C.

SN54BCT2524 SN74BCT25244 (OR	
1Y1 [1 U	24	1OE
GND [2	23	1A1
1Y2 🛛	3	22	1A2
1Y3 🛛	4	21	V _{CC}
GND [5	20	1A3
1Y4 🛛	6	19	1A4
2Y1 🛛	7	18	2A1
GND [8	17	2A2
2Y2 🛛	9	16	V _{CC}
2Y3 🛛	10	15	2A3
GND 🛛	11	14	2A4
		ь	

SN54BCT25244 ... FK PACKAGE (TOP VIEW)

13 20E

2Y4 🛛 12



NC - No internal connection

(each buffer/driver)										
INP	JTS	OUTPUT								
OE	Α	Y								
L	Н	Н								
L	L	L								
Н	Х	Z								

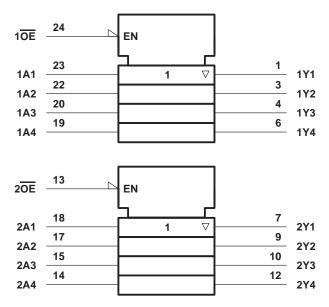
FUNCTION TABLE

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54BCT25244, SN74BCT25244 25- Ω OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

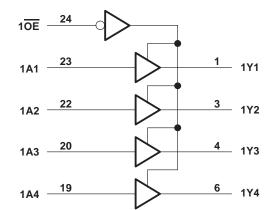
SCBS064A - JUNE 1990 - REVISED NOVEMBER 1993

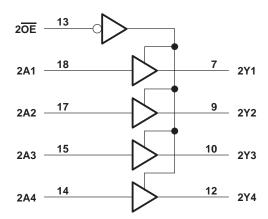
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	-0.5 V/ to 7 V/
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the disabled or power-off state, V _O	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, V _O	\dots -0.5 V to V _{CC}
Input clamp current, I _{IK} (VI < 0)	
Current into any output in the low state, I _O : SN54BCT25244	250 mA
SN74BCT25244	
Operating free-air temperature range: SN54BCT25244	–55°C to 125°C
SN74BCT25244	
Storage temperature range	−65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



SN54BCT25244, SN74BCT25244 **25-**Ω OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS064A - JUNE 1990 - REVISED NOVEMBER 1993

recommended operating conditions (see Note 2)

		SN54BCT25244			SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
Iк	Input clamp current			-18			-18	mA
IOH	High-level output current			-53			-80	mA
IOL	Low-level output current			125			188	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	тес	SN5	4BCT25	244	SN7	244	UNIT		
PARAMETER	TES	TEST CONDITIONS				MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.2			-1.2	V
	V _{CC} = 4.75 V,	I _{OH} = – 3 mA				2.7			
VOH	V _{CC} = 4.5 V	I _{OH} = -53 mA	2						V
	VCC = 4.5 V	I _{OH} = -80 mA				2			
		I _{OL} = 94 mA		0.38	0.55		0.42	0.55	
VOL	V _{CC} = 4.5 V	I _{OL} = 125 mA			0.8				V
		I _{OL} = 188 mA						0.7	
lj	V _{CC} = 5.5 V,	V _I = 5.5 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
۱ _{IL}	V _{CC} = 5.5 V,	V _I = 0.5 V			-0.6			-0.6	mA
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.5 V			-50			-50	μΑ
ICCL	V _{CC} = 5.5 V,	Outputs open		90	119		90	119	mA
ІССН	V _{CC} = 5.5 V,	Outputs open		59	78		59	78	mA
ICCZ	V _{CC} = 5.5 V,	Outputs open		7	11		7	11	mA
Ci	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		5.5			5.5		pF
Co	V _{CC} = 5 V,	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$		17			17		рF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(Tj	CC = 5 V A = 25°C	;	SN54BC1	25244	SN74BC	Г25244	UNIT
	(INFOT)	(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	Y	1	3.2	4.9	1	5.6	1	5.5	ns
^t PHL	A		2	4	5.6	2	6.3	2	6	
^t PZH	05	V	3.2	5.6	8.5	3.2	9.7	3.2	9.3	20
^t PZL	OE	Y	3.7	6.3	9.2	3.7	10.4	3.7	10.2	ns
^t PHZ	ŌĒ	v	1.6	3.6	5.5	1.6	6.5	1.6	6.3	20
tPLZ	UE UE	ſ	3.1	5.3	7.8	3.1	9.5	3.1	8.4	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74BCT25244DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT25244	Samples
SN74BCT25244DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT25244	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



www.ti.com

PACKAGE OPTION ADDENDUM

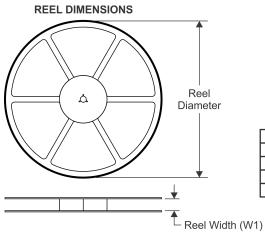
10-Dec-2020

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT25244DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

14-Feb-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT25244DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated